

# SOT577-2

plastic rectangular-DIL-bent-SIL power package; 17 leads  
(row spacing 2.54 mm)

16 October 2018

Package information

## 1 Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	RDBS17P
Package type industry code	RDBS17P
Package style descriptive code	RDBS (right-angle DIL-bent-SIL)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-03-2003
Manufacturer package code	SOT577

Table 1. Package summary

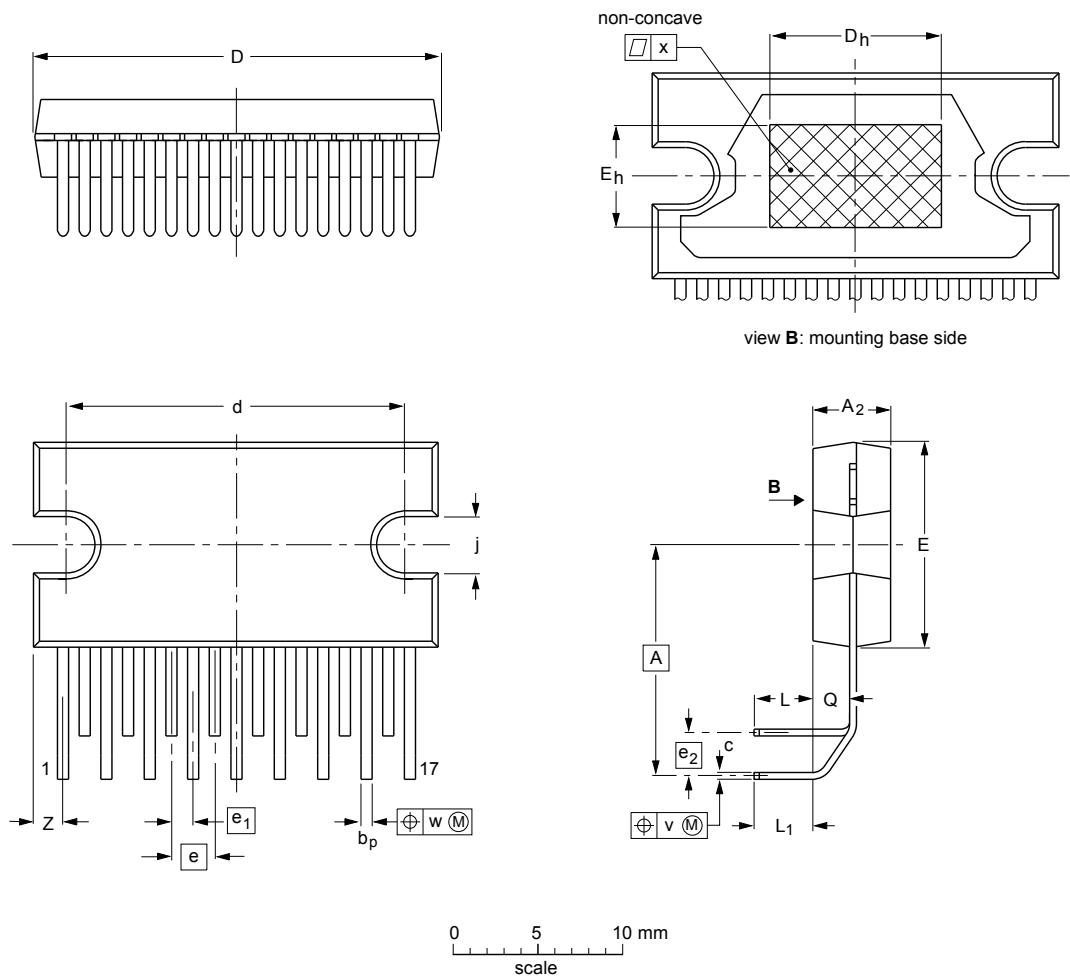
Parameter	Min	Nom	Max	Unit
package length	23.6	23.8	24	mm
package width	11.8	12	12.2	mm
package height	4.4	4.5	4.6	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	17	-	



2 Package outline

RDBS17P: plastic rectangular-DIL-bent-SIL power package; 17 leads (row spacing 2.54 mm)

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>2</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	d	D <sub>h</sub>	E <sup>(1)</sup>	e	e <sub>1</sub>	e <sub>2</sub>	E <sub>h</sub>	j	L	L <sub>1</sub>	Q	v	w	x	Z <sup>(1)</sup>
mm	13.5	4.6 4.4	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	2.54	1.27	2.54	6	3.4 3.1	3.75 3.15	3.75 3.15	2.1 1.8	0.6	0.4	0.03	2.00 1.45

Note  
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT577-2						-01-01-05- 03-03-12

Figure 1. Package outline RDBS17P (SOT577-2)

### 3 Legal information

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